

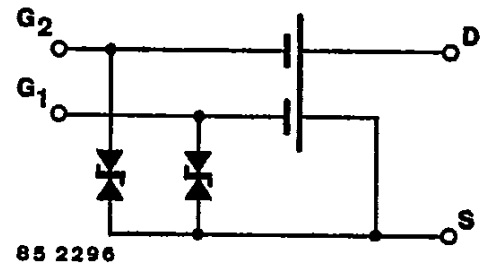
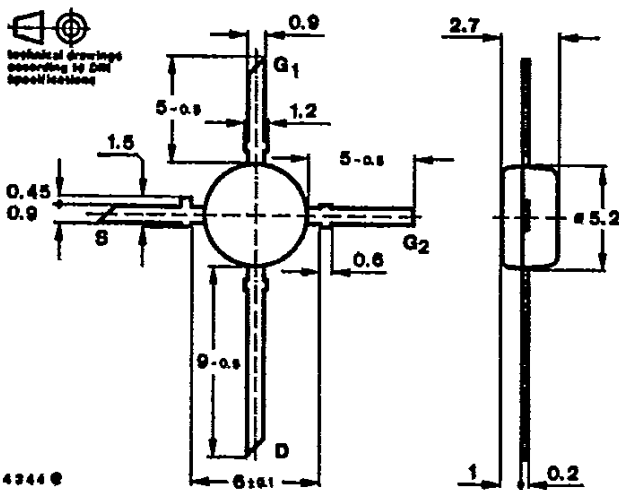
**N-Channel Dual Gate MOS-Fieldeffect Tetrode · Depletion Mode**

**Applications:** Input- and Mixerstages especially for UHF-tuners

**Features:**

- Integrated Gate protection diodes
- High cross modulation performance
- Low noise figure
- High AGC-range
- Low feedback capacitance
- Low input capacitance

**Dimensions in mm**



Case  
50 B 4 DIN 41 867  
JEDEC TO 50  
Weight max. 0.1 g

**Absolute maximum ratings**

Drain Source Voltage	$V_{DS}$	20	V
Drain current	$I_D$	30	mA
Gate 1/Gate 2-Source peak current	$\pm I_{G1/2SM}$	10	mA
Total power dissipation $T_{amb} = 60^\circ C$	$P_{tot}$	200	mW
Channel temperature	$T_C$	150	$^\circ C$
Storage temperature range	$T_{stg}$	-55 ... +150	$^\circ C$

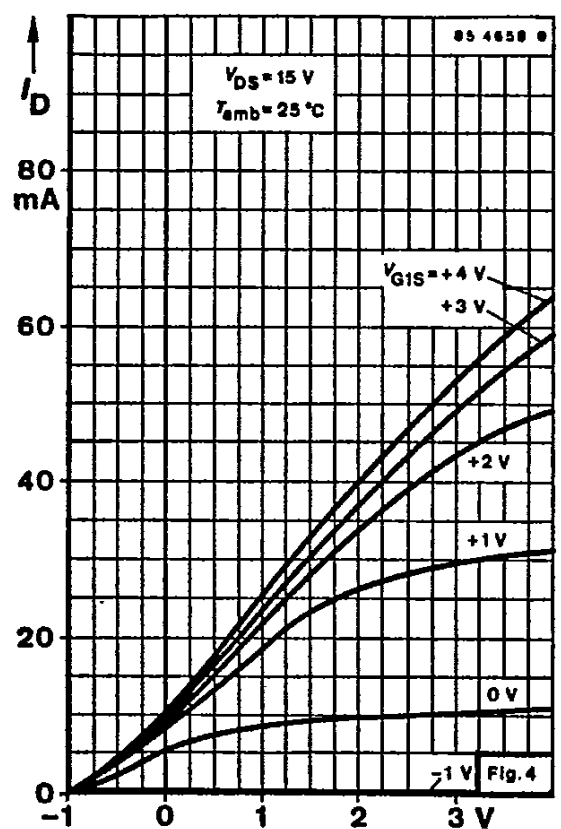
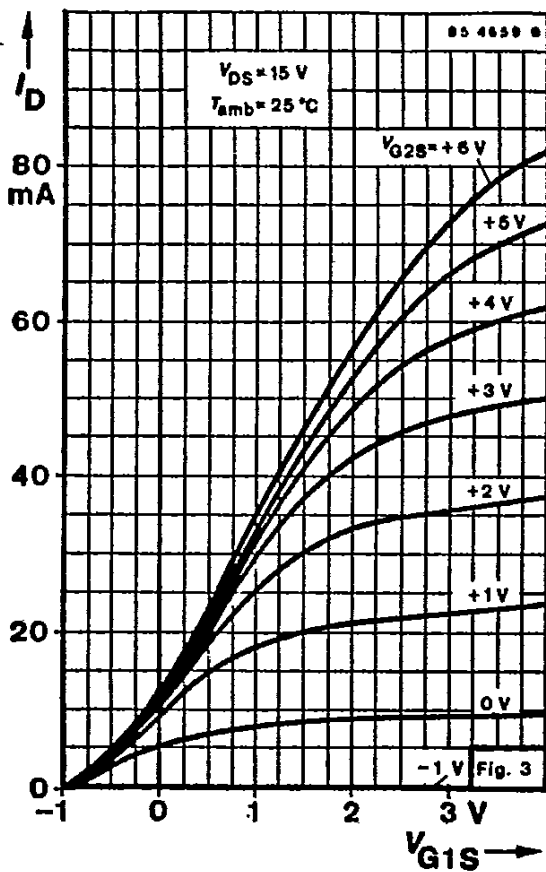
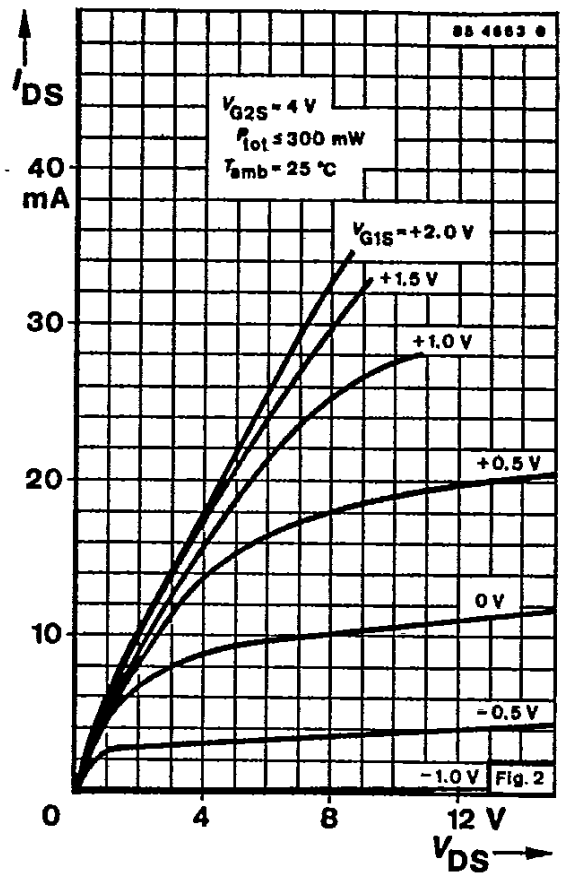
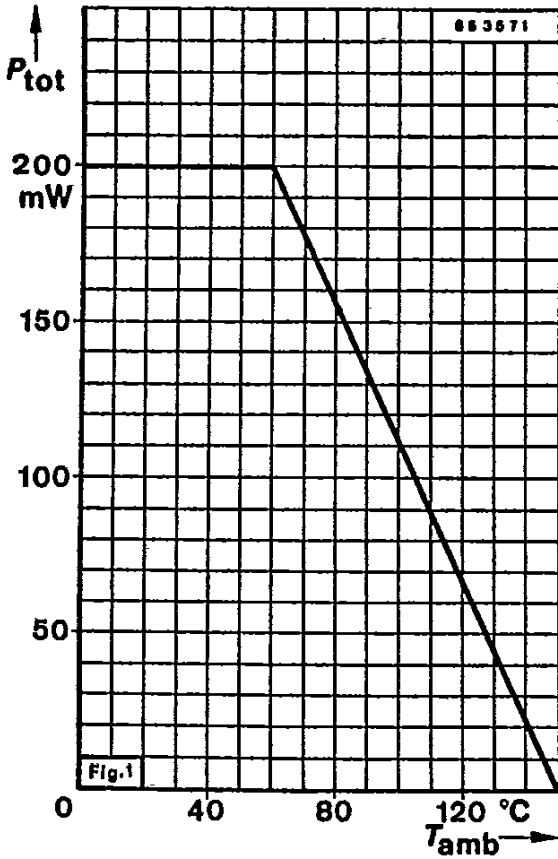
**Thermal resistance**

	Min.	Typ.	Max.
Channel ambient mounted on pc-board one side Cu 35 $\mu m$ thickness 40 x 25 x 1.5 mm <sup>3</sup>			450 K/W
		$R_{thCA}$	

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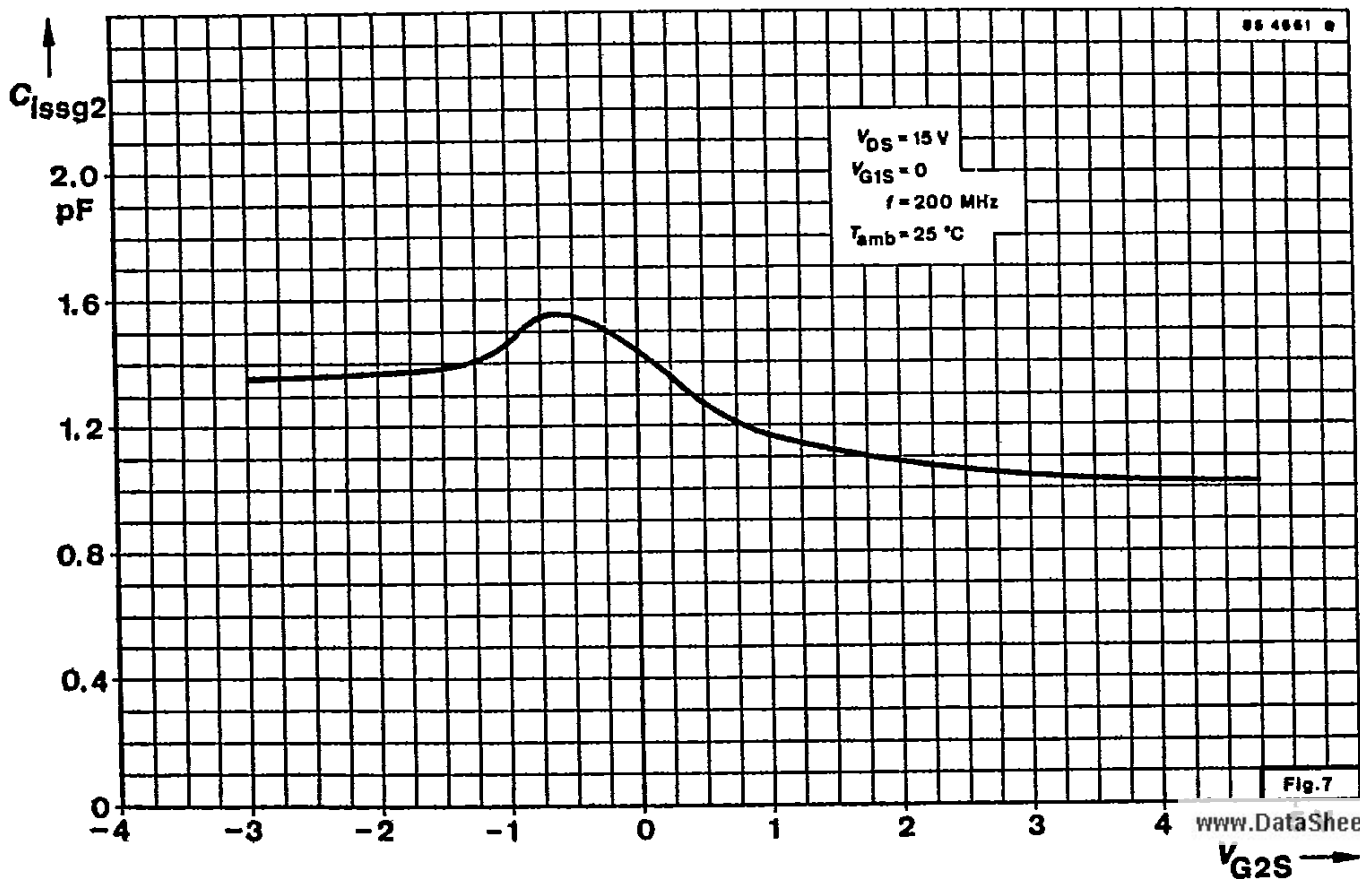
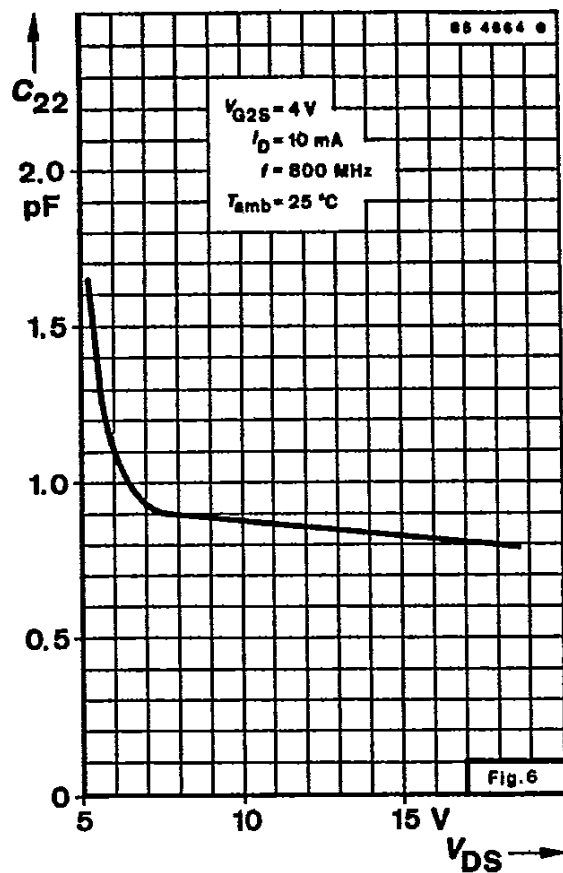
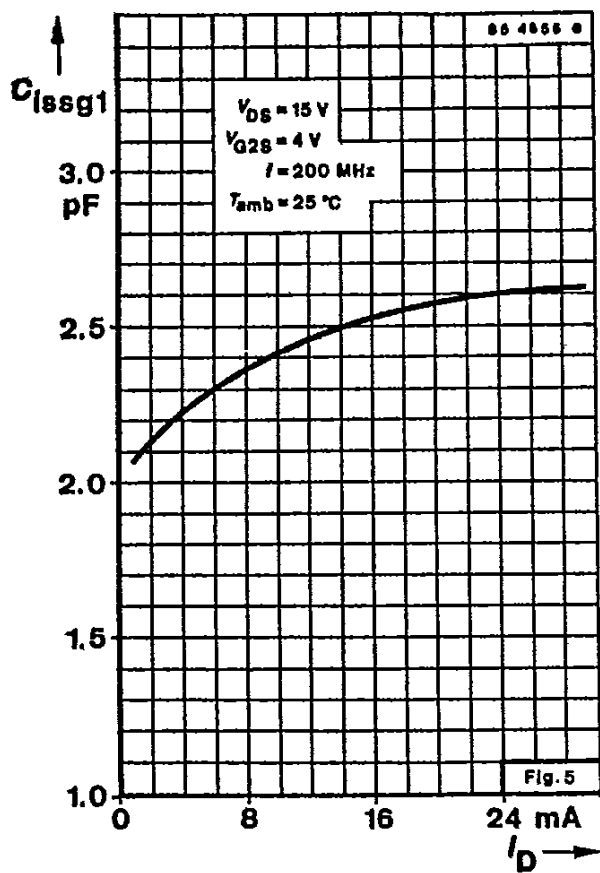
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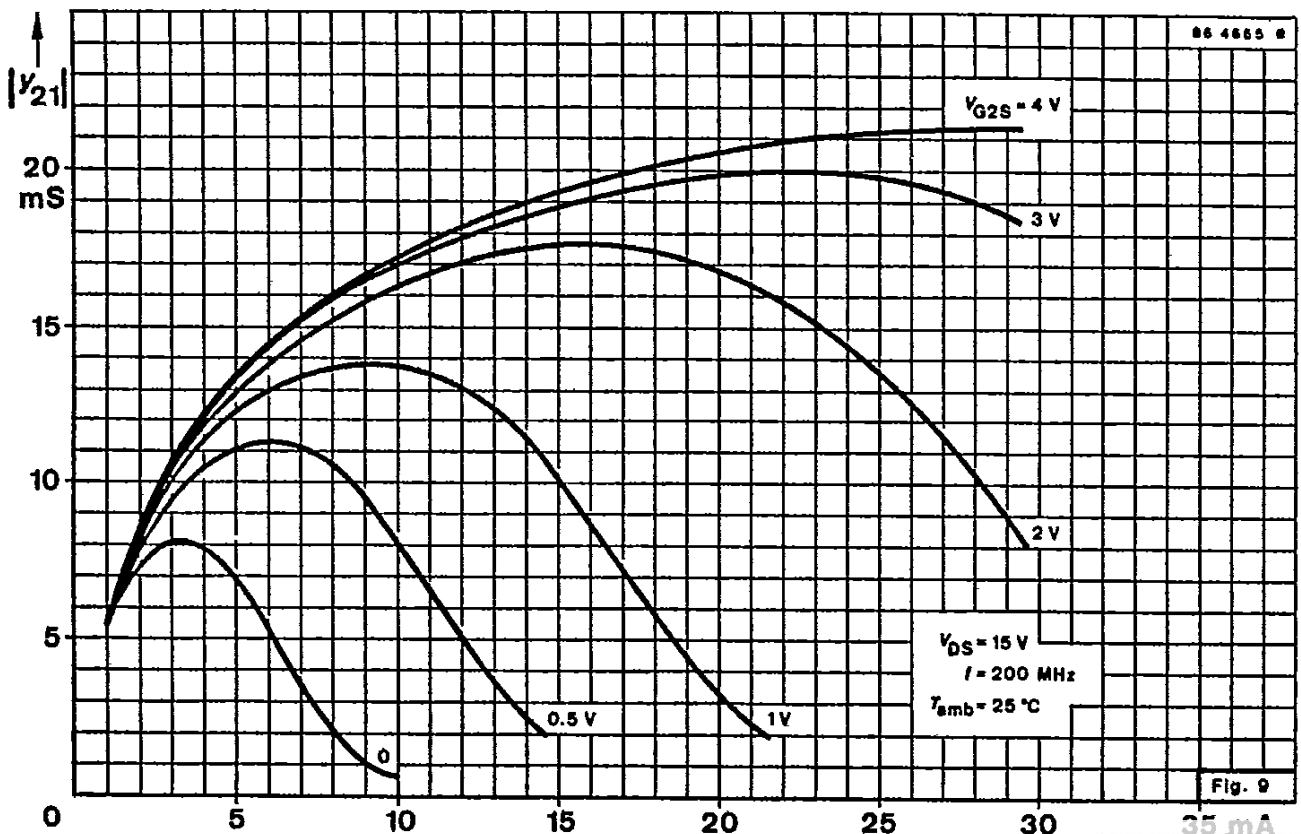
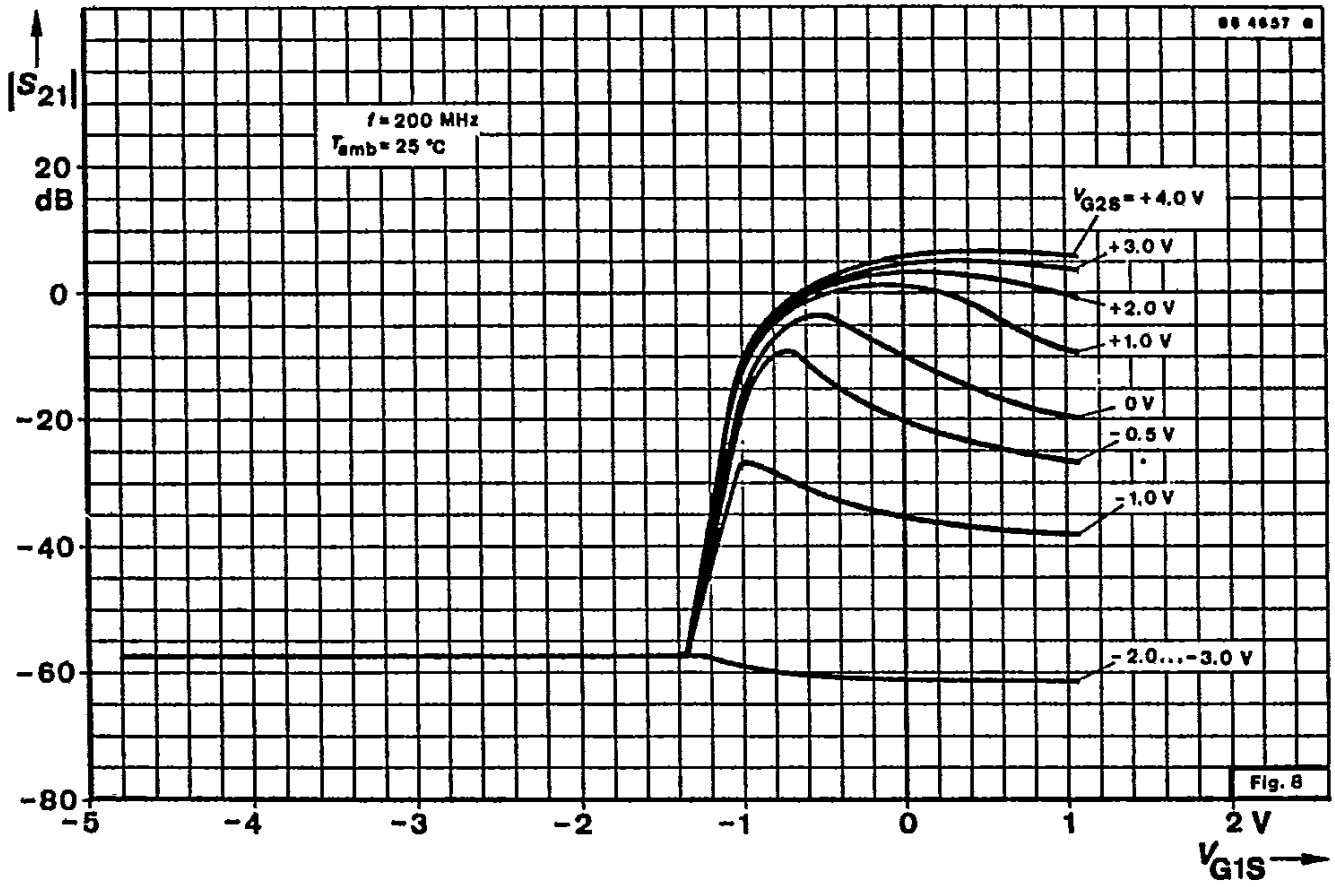
DC characteristics		Min.	Typ.	Max.
$T_{amb} = 25\text{ }^{\circ}\text{C}$ , unless otherwise specified				
Drain-source breakdown voltage $I_D = 10\text{ }\mu\text{A}$ , $-V_{G1S} = -V_{G2S} = 4\text{ V}$	$V_{(BR)DS}$	20		V
Gate 1-Source breakdown voltage $\pm I_{G1S} = 10\text{ mA}$ , $V_{G2S} = V_{DS} = 0$	$\pm V_{(BR)G1SS}$	6		20 V
Gate 2-Source breakdown voltage $\pm I_{G2S} = 10\text{ mA}$ , $V_{G1S} = V_{DS} = 0$	$\pm V_{(BR)G2SS}$	6		20 V
Gate 1-Source cut-off current $\pm V_{G1S} = 5\text{ V}$ , $V_{G2S} = V_{DS} = 0$	$I_{G1SS}$			50 nA
Gate 2-Source cut-off current $\pm V_{G2S} = 5\text{ V}$ , $V_{G1S} = V_{DS} = 0$	$I_{G2SS}$			50 nA
Drain current $V_{DS} = 15\text{ V}$ , $V_{G1S} = 0$ , $V_{G2S} = 4\text{ V}$	$I_{DSS}$	2		20 mA
Gate 1-Source cut-off voltage $V_{DS} = 15\text{ V}$ , $V_{G2S} = 4\text{ V}$ , $I_D = 20\text{ }\mu\text{A}$	$-V_{G1S(OFF)}$			2.5 V
Gate 2-Source cut-off voltage $V_{DS} = 15\text{ V}$ , $V_{G1S} = 0\text{ V}$ , $I_D = 20\text{ }\mu\text{A}$	$-V_{G2S(OFF)}$			2.0 V
<b>AC characteristics</b>				
$V_{DS} = 15\text{ V}$ , $I_D = 10\text{ mA}$ , $V_{G2S} = 4\text{ V}$ , $f = 1\text{ MHz}$ , $T_{amb} = 25\text{ }^{\circ}\text{C}$ , unless otherwise specified				
Forward transadmittance	$ y_{21} $	15	17	mS
Gate 1-Input capacitance	$C_{ISSG1}$		2.2	2.6 pF
Gate 2-Input capacitance $V_{G1S} = 0$ , $V_{G2S} = 4\text{ V}$	$C_{ISSG2}$		1.1	pF
Feedback capacitance	$C_{rSS}^{1)}$		25	35 fF
Output capacitance	$C_{OSS}$		0.8	1.2 pF
<b>Power gain</b>				
$V_{DS} = 15\text{ V}$ , $I_D = 10\text{ mA}$ , $V_{G2S} = 4\text{ V}$ , $g_G = 2\text{ mS}$ , $g_L = 0.5\text{ mS}$ , $f = 200\text{ MHz}$	$G_{ps}$		25	dB
$g_G = 3.3\text{ mS}$ , $g_L = 1\text{ mS}$ , $f = 800\text{ MHz}$	$G_{ps}$		18	dB
<b>Noise figure</b>				
$V_{DS} = 15\text{ V}$ , $I_D = 10\text{ mA}$ , $V_{G2S} = 4\text{ V}$ , $g_G = 2\text{ mS}$ , $f = 200\text{ MHz}$	$F$		1.0	dB
$f = 800\text{ MHz}$	$F$		1.8	dB



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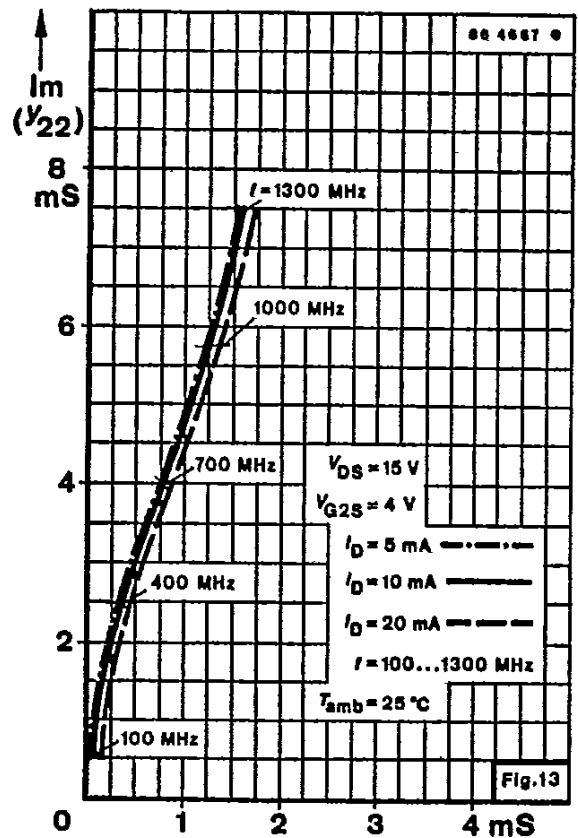
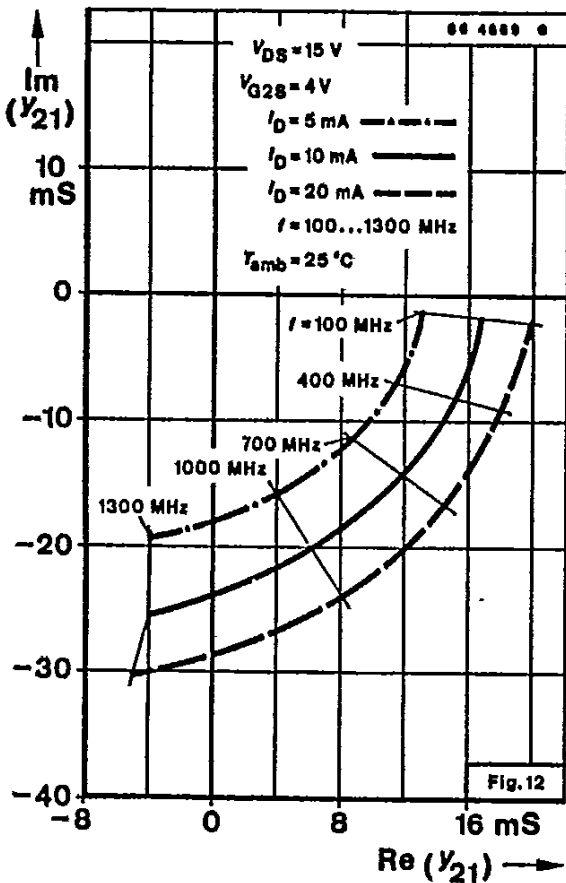
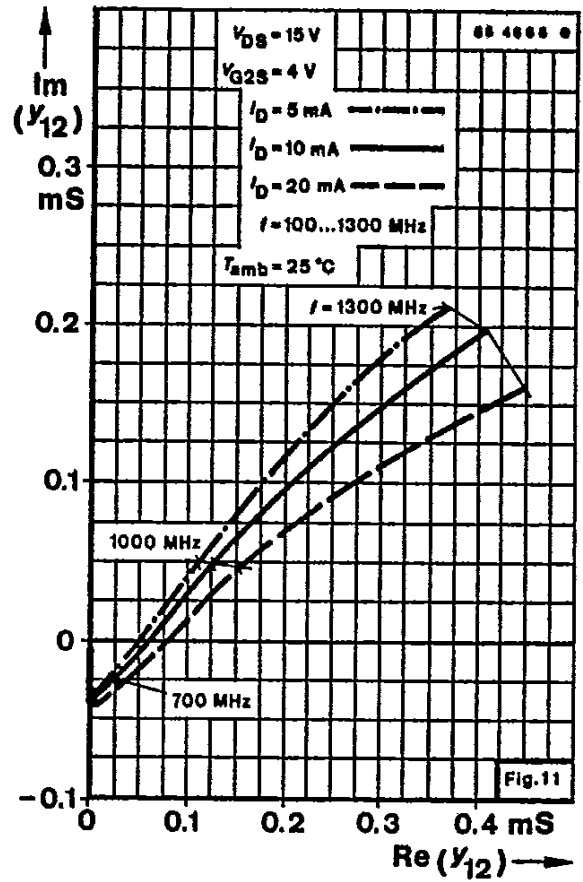
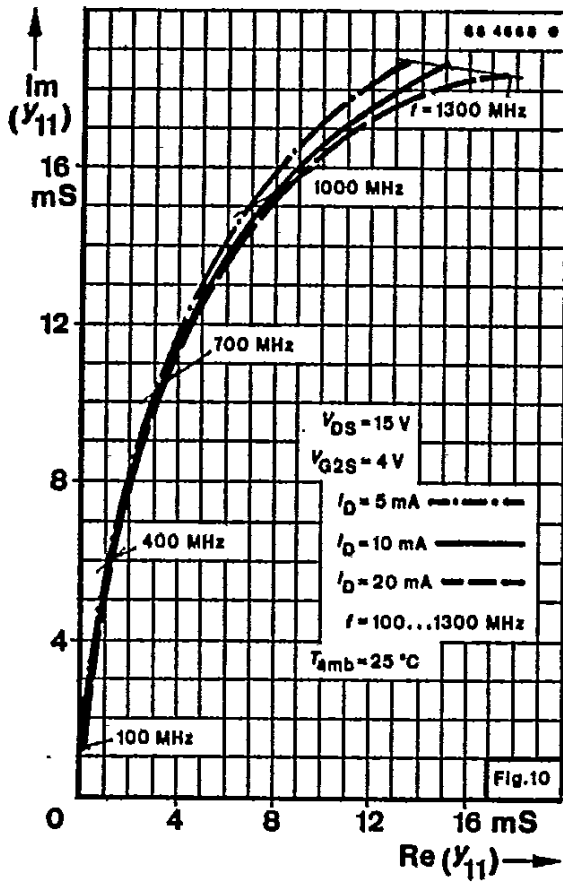
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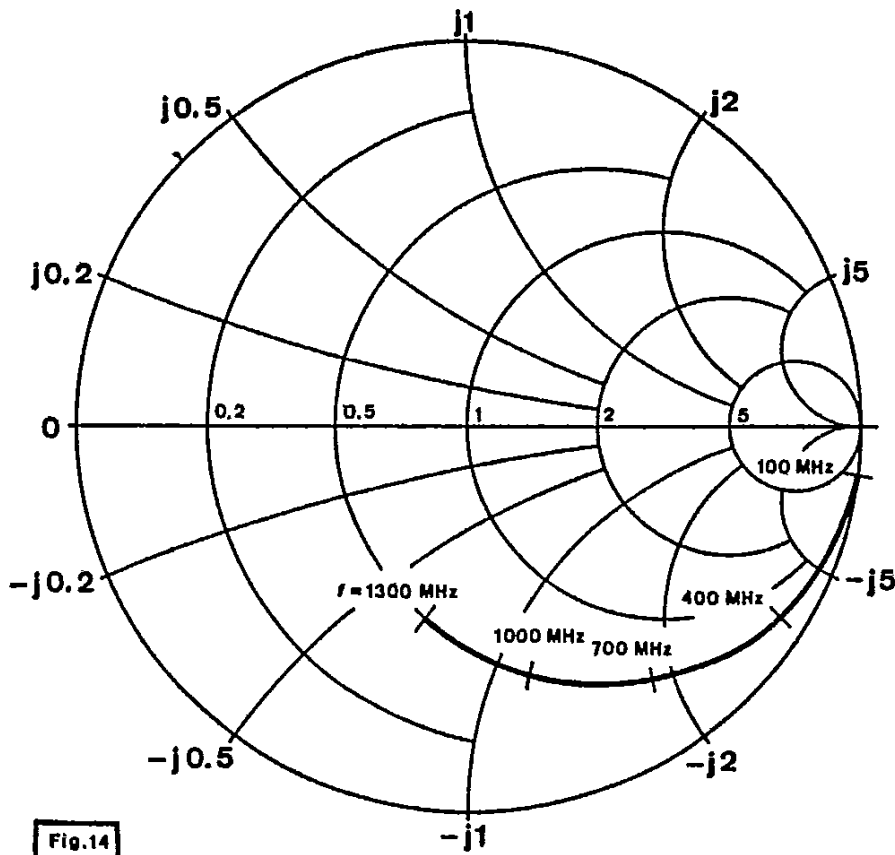




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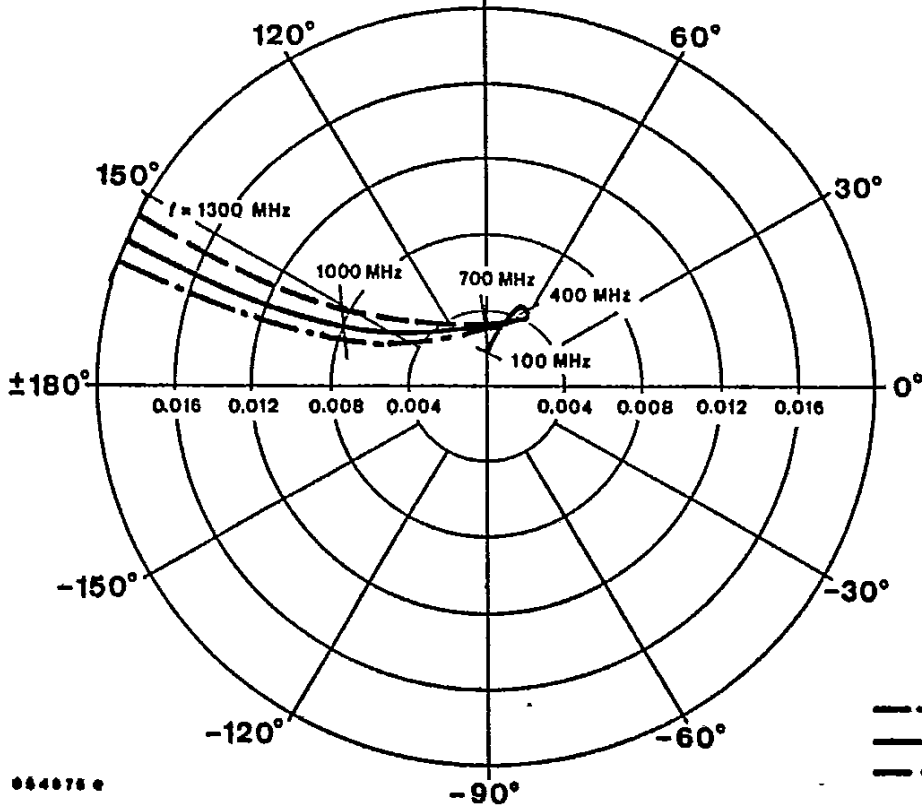
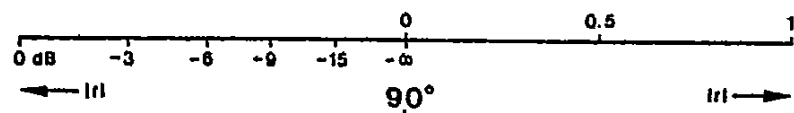




**S<sub>11</sub>**  
 $I_D = 10 \text{ mA}$   
 $V_{DS} = 15 \text{ V}$   
 $V_{G2S} = 4 \text{ V}$   
 $Z_0 = 50 \Omega$   
 $f = 100 \dots 1300 \text{ MHz}$   
 $T_{amb} = 25^\circ \text{C}$

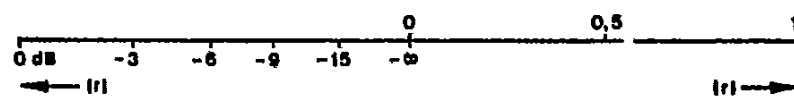
**Fig.14**

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**S<sub>12</sub>**  
 $Z_0 = 50 \Omega$   
 $V_{DS} = 15 \text{ V}$   
 $V_{G2S} = 4 \text{ V}$   
 - - -  $I_D = 5 \text{ mA}$   
 —  $I_D = 10 \text{ mA}$   
 - - -  $I_D = 20 \text{ mA}$   
 $f = 100 \dots 1300 \text{ MHz}$   
 $T_{amb} = 25^\circ \text{C}$

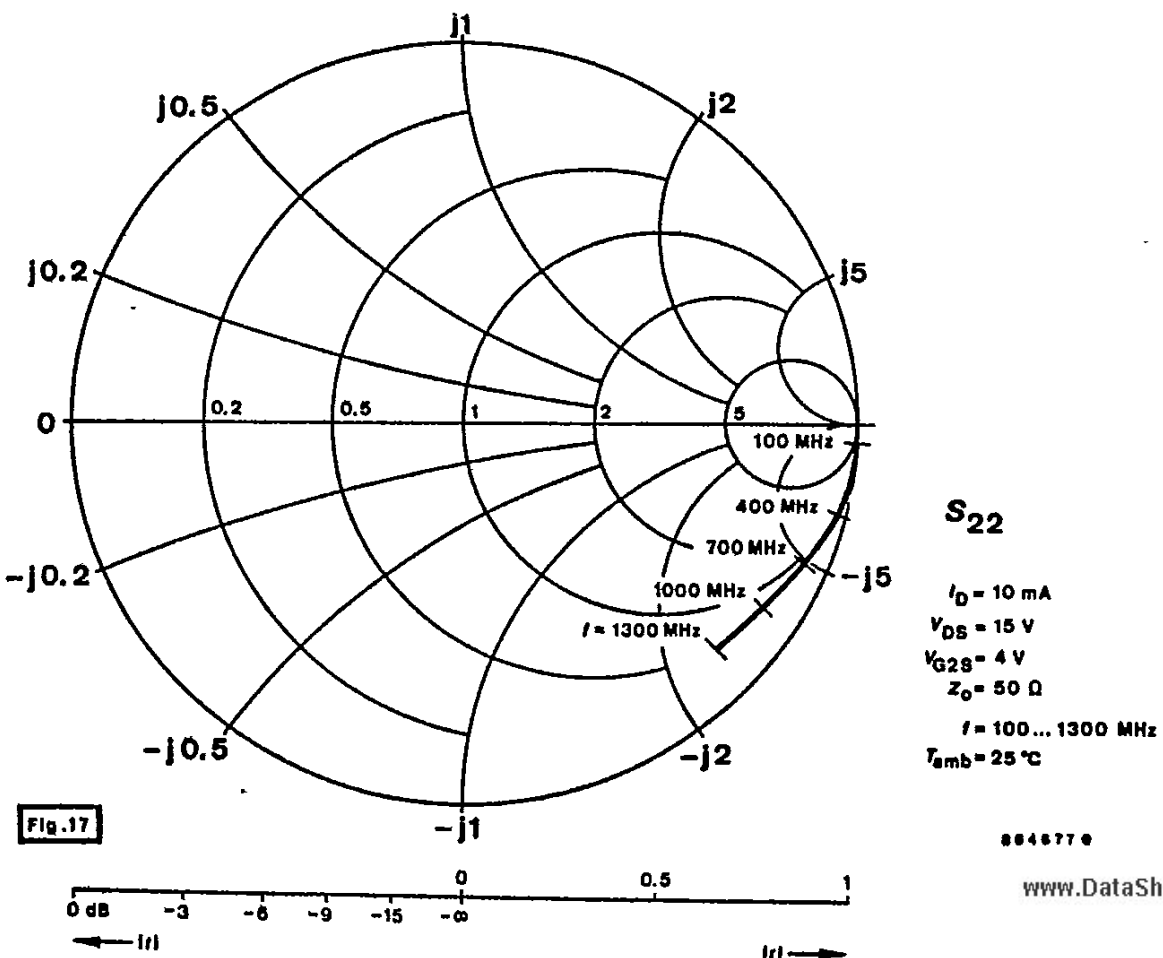
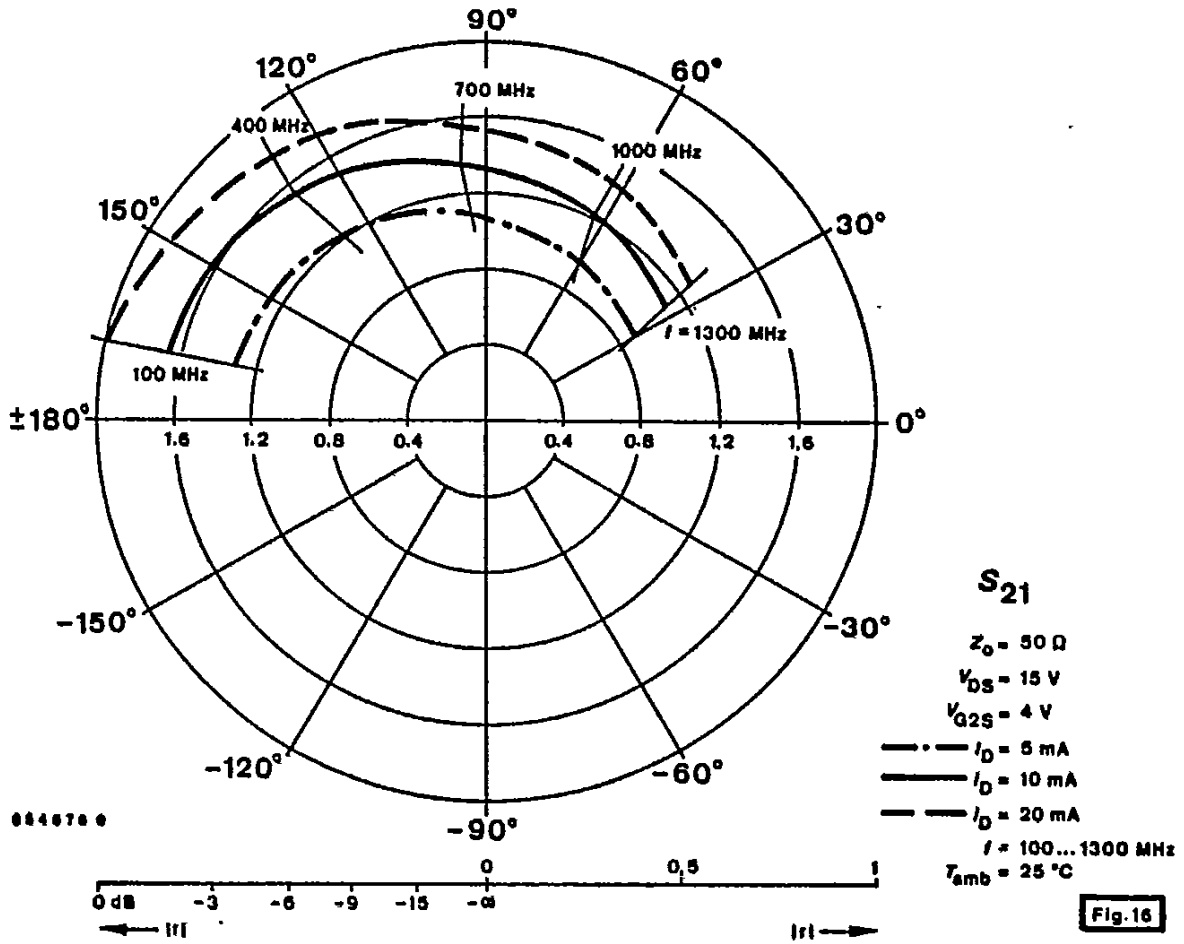
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**Fig.15**

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## 7. Taping and Reeling

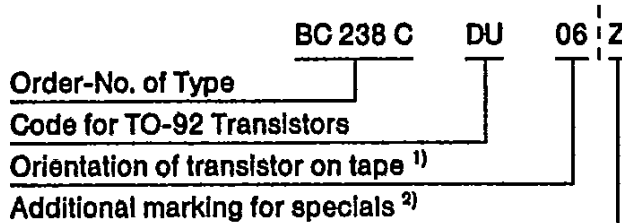
### 7.1. Taping of TO-92 Transistors

Standard reeling: Taped on reel, reeled together with a paper film.

#### 7.1.1. Order Numbers

Add the taping-code to the order number.

Example:



<sup>1)</sup> 06 = View on flat side of transistor, view on gummed tape

05 = View on round side of transistor, view on gummed tape

<sup>2)</sup> Additional marking "0": taping without paper film

Additional marking "Z": Zigzag folded tape in special box. Marking for orientation of transistor not necessary, because box can be opened on top or bottom

Example for order No.: BC 237 C DU Z

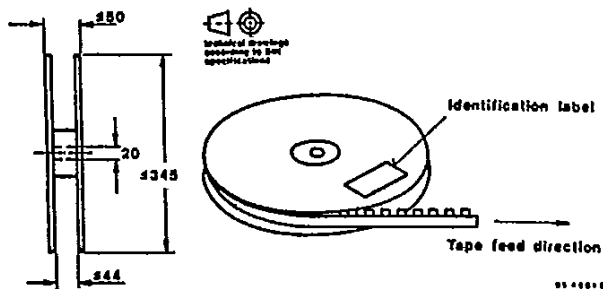


Fig. 7.1. Dimensions of reel in mm

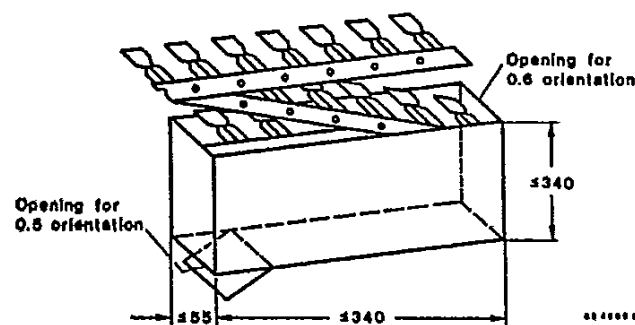


Fig. 7.2. Dimension of box for Zigzag folding in mm

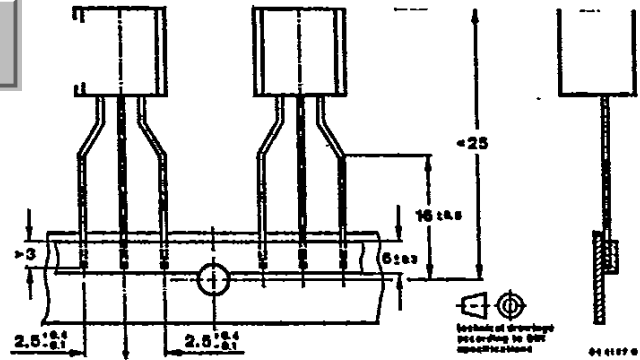


Fig. 7.3. Dimensions of tape in mm

#### 7.1.2. Quantity of devices

1 000 devices per reel

2 000 devices per folded tape in special box.

### 7.2. Taped transistors in SOT 23 and SOT 143 case

#### 7.2.1. Designation

##### a) Standard taping

Designation is attached with code GS 08 in case of standard taping. Example for normal version transistors as standard taped: BF 569-GS 08.

Example for R-version transistors as standard taped: BF 569 R-GS 08.

In case of standard taping, the transistor orientation on the tape is shown in Fig. 7.4 and Fig. 7.5.

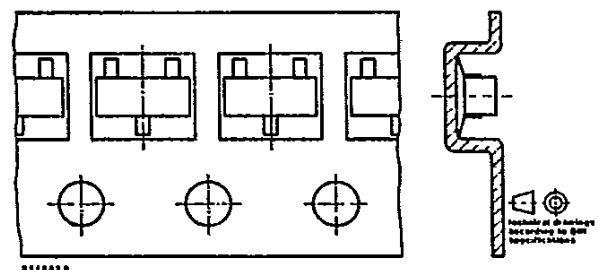


Fig. 7.4. Standard taped SOT 23

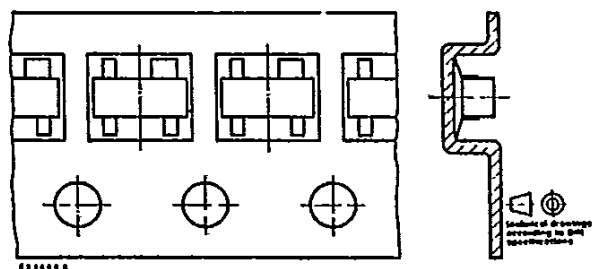


Fig. 7.5. Standard taped SOT 143

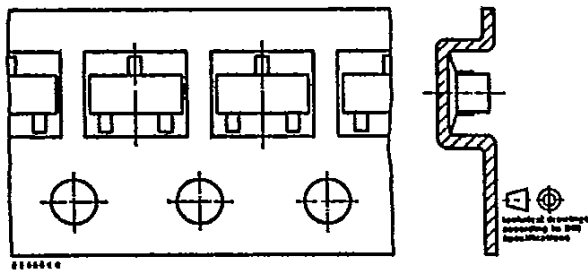
**b) Reverse taping**

Designation is attached with code GS 07 in case of reverse taping. Example for normal version transistors as reverse taped: BF 569-GS 07.

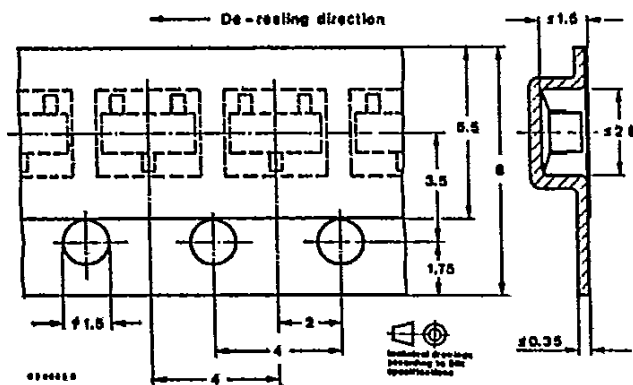
Example for R-version transistors as reverse taping: BF 569 R-GS 07.

In case of reverse taping, the transistor orientation on the tape is shown in Fig. 7.6.

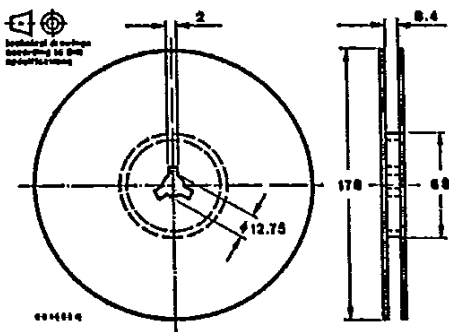
Regarding MOS-FET and MES-FET devices, reverse taping is at present not available.



**Fig. 7.6 Reverse taped SOT 23**



**Fig. 7.7 Dimensions of tape in mm**



**Fig. 7.8 Dimensions of reel in mm**

**7.2.2 Quantity of devices**

**3000 devices per reel**